The Institute for Interconnecting and Packaging Electronic Circuits
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IPC-TM-650
TEST METHODS MANUAL

Number **2.4.10**	
Subject **Plating Adhesion**	
Date **4/73**	Revision
Originating Task Group **N/A**	

1.0 Scope To test the adhesion of plating on printed wiring conductor patterns.

2.0 Applicable Documents

2.1 IPC-A-600A Acceptability Guidelines

2.2 Federal Specification L-T-90 ''Tape, Cellophane, Pressure Sensitive''

3.0 Test Specimen Use test specimen ''B'' of MLB Test Panel, section 5.8.3 of this publication, or a production board.

4.0 Apparatus Not applicable.

5.0 Procedure

5.1 Test

5.1.1 Firmly press a 1/2 in. strip of pressure-sensitive cellophane tape across the surface of the conductor pattern.

5.1.2 Remove the tape rapidly by manual force applied approximately perpendicular to the pattern.

5.1.3 The tape must be applied to, and removed from, three different locations on each printed wiring board tested.

5.1.4 Fresh tape shall be used for each test.

5.2 Evaluation Examine for any portions of the protective plating or the conductor pattern being removed, as shown by particles of the plating or pattern adhering to the tape. If overhanging metal breaks off (slivers) and adheres to the tape, it is evidence of overhang but not of plating adhesion failure.